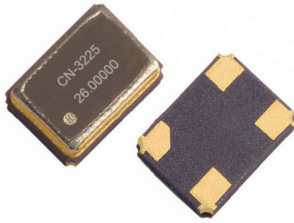


X32F

**Description:**



- Ultra-Miniature Size
- Mobile Communications Applications
- Highly Precise
- GSM
- Ceramic Package
- PDC
- Tape and Reel
- CDMA
- Reflow Soldering
- PHS

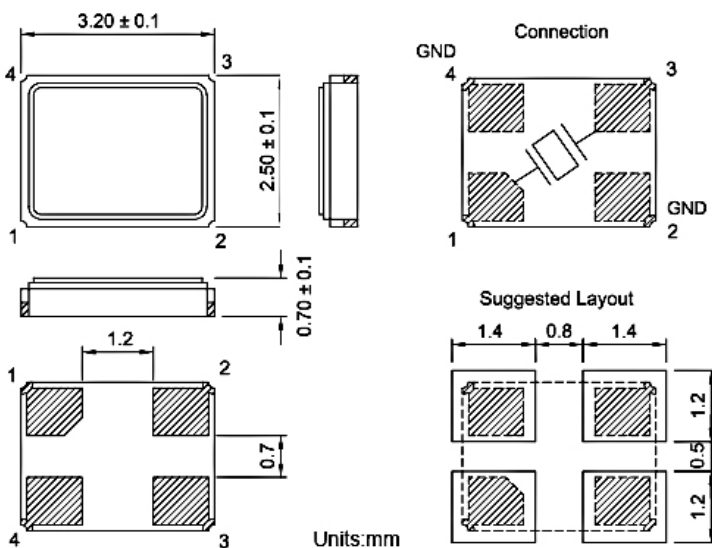
**Performance Characteristics**

Parameter		X32F
Frequency Range	F <sub>0</sub>	12.000MHz~39.000MHz
Mode of Vibration		Fundamental      Overtone
Resonance Resistance	R <sub>r</sub>	80Ω Max
Frequency Tolerance (at 25°C)		±5×10 <sup>-6</sup> ~±30×10 <sup>-6</sup>
Storage Temperature Range	T <sub>STG</sub>	-55°C~+125°C
Shunt Capacitance	C <sub>0</sub>	7pF Max
Load Capacitance	CL	8pF~50pF or Series
Insulation Resistance	IR	>500MΩ DC/100V±10V
Drive Level	DL	0.01mW~0.1mW
Aging	Fa	±3×10 <sup>-6</sup> ~±5×10 <sup>-6</sup> /year

**Frequency Stability Over Temperature Range**

Temperature Range	Frequency Stability				
	O:±5×10 <sup>-6</sup>	P:±15×10 <sup>-6</sup>	Q:±20×10 <sup>-6</sup>	S:±30×10 <sup>-6</sup>	T:±50×10 <sup>-6</sup>
A: 0°C~+50°C	●	●	●	●	●
B: -10°C~+60°C	●	●	●	●	●
C: -20°C~+70°C		●	●	●	●
G: -40°C~+85°C			●	●	●

**Outline Drawing (mm)**



PAD NO.	CONNECTION
#1	INPUT
#2	GND
#3	OUTPUT
#4	GND